

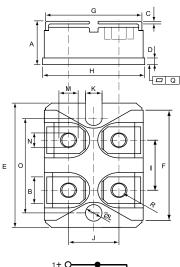
# CSRI4×25-065L1B

### SiC Schottky Diode Full Bridge Power Module

Preliminary

### Vrrm=650V I⊧=25A@Tc=135℃







DIMENSIONS						
	INC	IES	М	М		
	MIN	MAX	MIN	MAX		
Α	0.460	0.483	11.68	12.28		
В	0.307	0.323	7.80	8.20		
С	0.030	0.033	0.75	0.85		
D	0.071	0.081	1.80	2.05		
Е	1.488	1.504	37.80	38.20		
F	1.248	1.260	31.70	32.00		
G	0.917	0.957	23.30	24.30		
Н	0.996	1.008	25.30	25.60		
I	0.579	0.602	14.70	15.30		
J	0.492	0.516	12.50	13.10		
К	0.161	0.169	4.10	4.30		
L	0.161	0.169	4.10	4.30		
М	0.181	0.197	4.60	5.00		
Ν	0.165	0.181	4.20	4.60		
0	1.181	1.197	30.00	30.40		
Q	-0.002	0.004	-0.05	0.10		
R	M4*8					

# Features

- Zero reverse recovery
- Zero forward recovery
- Temperature-independent switching behavior
- Positive temperature coefficient on VF
- Very low stray inductance
- High level of integration

### **Benefits**

- Outstanding performance at high-frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction-to-case thermal resistance
- RoHS compliant

### **Applications**

- Switch mode power supplies rectifier
- Induction heating
- Welding equipment
- High-speed rectifiers

### **Maximum Ratings**

Part Number	Maximum Recurrent Peak Reverse Voltage	Maximum DC Blocking Voltage	
CSRI4×25-065L1B	650V	650V	

Maximum Rating	Symbol	Conditions	Value	Unit	
Continuous forward current (per diode)	I <sub>F</sub>	T <sub>C</sub> =135 °C	25		
Surge non-repetitive forward current	I <sub>FSM</sub>	T <sub>C</sub> =25 °C, t <sub>p</sub> =8.3 ms	200		
sine halfwave (per diode)	1 OM	T <sub>C</sub> =150 °C, t <sub>p</sub> =8.3 ms	125	А	
Non-repetitive peak forward current	I <sub>F,max</sub>	T <sub>C</sub> =25 °C, t <sub>p</sub> =10 $\mu$ s	800	800	
(per diode)		T <sub>C</sub> =150 °C, t <sub>p</sub> =10 $\mu$ s	500		
Repetitive peak reverse voltage V <sub>RRM</sub>		T <sub>j</sub> =25 °C	650	V	
Isolation voltage between All Terminals and Baseplate		50/60 Hz, t=1min I <sub>ISOL</sub> ≤ 1mA	2500	V	
Mounting torque		To heatsink	1.3	Nm	
		To terminal	1.1		



#### **Electrical Characteristics**, at $T_j$ =25 °C, unless otherwise specified. (per diode)

Static Characteristics	Symbol	Conditions	Values			
			min.	typ.	max.	Unit
DC blocking voltage	V <sub>DC</sub>		650	-	-	
Diode forward voltage	V <sub>F</sub>	I <sub>F</sub> =25A, T <sub>j</sub> =25 °C	-	1.50	1.70	V
		I <sub>F</sub> =25A, T <sub>j</sub> =175 °C	-	1.70	2.00	
Reverse current	IR	V <sub>R</sub> =650V, T <sub>j</sub> =25 °C	-	25	50	
		V <sub>R</sub> =650V, T <sub>j</sub> =175 °C	-	50	200	μA

#### AC Characteristics (per diode)

Static Characteristics	Symbol	Conditions	Values			
			min.	typ.	max.	Unit
Total capacitive charge	Q <sub>rr</sub>	V <sub>R</sub> =400V, T <sub>j</sub> =25 °C	-	44	-	nC
Total capacitance	С	V <sub>R</sub> =0V, f=1 MHz T <sub>j</sub> =25 °C	-	931	-	pF
		V <sub>R</sub> =200V, f=1 MHz T <sub>j</sub> =25 °C	-	168	-	
		V <sub>R</sub> =400V, f=1 MHz T <sub>j</sub> =25 °C	-	164	-	

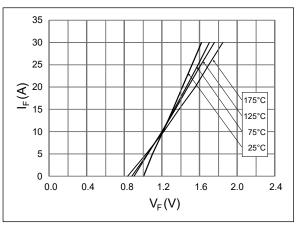
#### Thermal Characteristics (per diode)

Statia Characteriation	Cumple of	Values		
Static Characteristics	Symbol	typ.	Unit	
Thermal resistance from junction to case	$R_{ heta  JC}$	0.56	°C/W	Ī



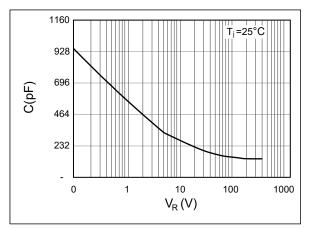
90 100

#### **Typical Performance**

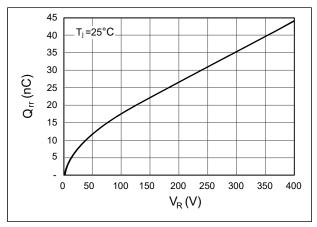


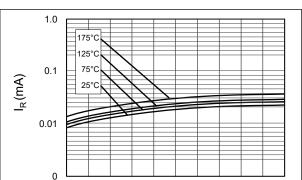
#### Forward Characteristics (parameterized on T<sub>j</sub>)

#### Capacitance

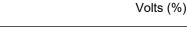


#### **Recovery Charge**





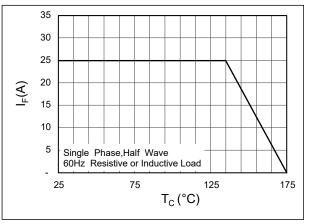
#### Reverse Characteristics (parameterized on Tj)

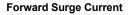


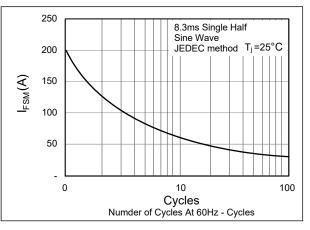
0 10

20 30 40 50 60 70 80

#### **Current Derating**









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